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EV318282163

#161A

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 10/004,172 ✓
Filing Date October 9, 2001
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner A.D. Tugbang
Attorney's Docket No. MI22-1839
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and Bonding
Frames

[Handwritten signature] 10/01/03

RESPONSE TO JUNE 4, 2003 OFFICE ACTION

To: Mail Stop Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

From: D. Brent Kenady
Tel. 509-624-4276; Fax 509-838-3424
Wells St. John P.S.
601 West First Avenue, Suite 1300
Spokane, WA 99201-3828

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TECHNOLOGY CENTER R3700

Responsive to the Office Action dated June 4, 2003, Applicant amends and
remarks as follows:

AMENDMENTS

Underlines indicate insertions and ~~strikeouts~~ indicate deletions.